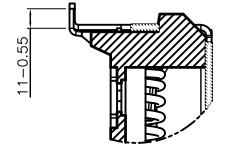
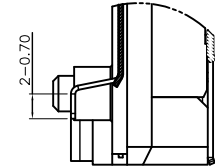


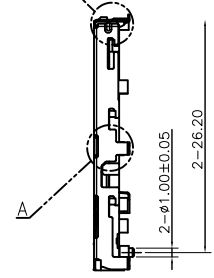
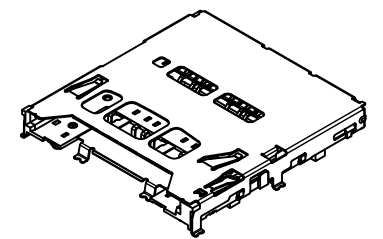
Detail E Scale 4:1



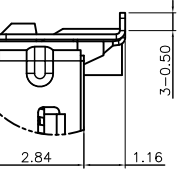
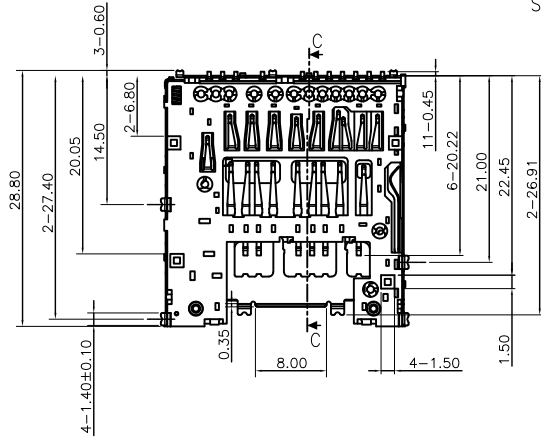
Detail D Scale 4:1



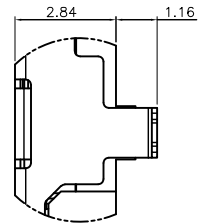
Detail F Scale 4:1



Detail B Scale 4:1



Detail A Scale 4:1



Detail C Scale 4:1

Note:

1. Material:

- 1-1. Plastic: HEAT RESISTANCE LCP, Black, HF, UL94V-0
- 1-2. Contact: Copper Alloy
- 1-3. Shell: Stainless Steel

2. Plating:

- 2-1. Contact: Contact Area: Au 1μ" min. Plating Over Ni 50μ" min. Solderable: Gold Flash Plating Over Ni 50μ" min.
- 2-2. Shell: Solderable Ni 50μ" min. Over All

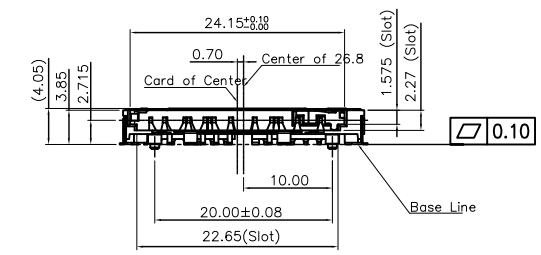
3. Contact And Soldertile Coplanarity to be 0.10mm max.

4. Electrical Characteristics:

- 4-1. Contact Current Rating:0.5Amperes.
- 4-2. Dielectric Withstanding Voltage:AC500V r. m. s.
- 4-3. Insulation Resistance:1000 Megohms
- 4-4. Contact Resistance:100 Miliohms Maximum.

5. Environmental:

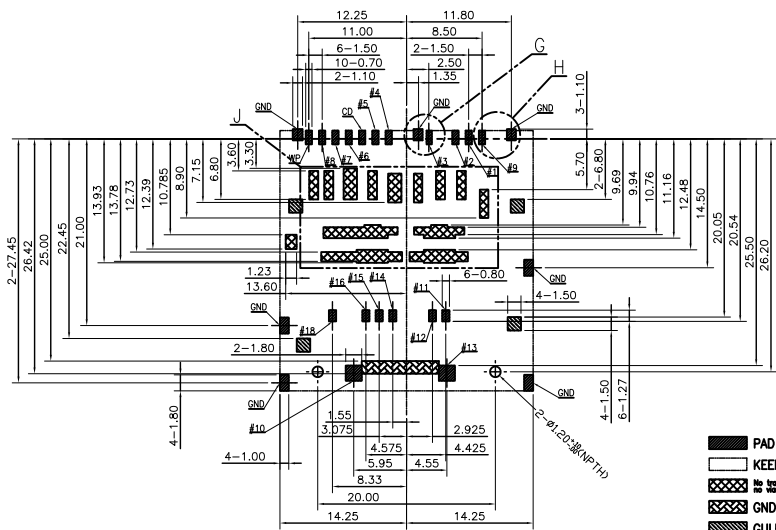
- 5-1. Operating Temperature:-25° C to +85° C.
- 5-2. Salty spray: 48H



Section C-C

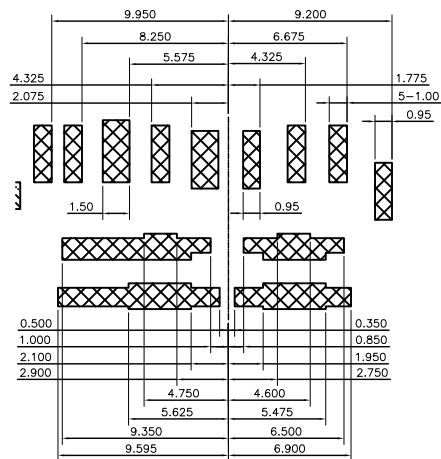
深圳市华宇创精密电子有限公司

<p>TOLERANCE:</p> <p>X.X ±0.30</p> <p>X.XX ±0.25</p> <p>X.XXX ±0.15</p> <p>X' ±2' X.X' ±0.5'</p> <p>UNIT: mm [inch]</p> <p>SCALE:1:1 SIZE: A4</p>	<p>DRAWN BY :</p> <p style="text-align: center;">陈一鸣</p>	<p>DATE :</p> <p style="text-align: center;">2014-02-23</p>	<p>PART NAME:</p> <p style="text-align: center;">SD 7.0 PUSH 4.0H SMT</p>
	<p>CHECKED BY:</p> <p style="text-align: center;">马跃</p>	<p>DATE :</p> <p style="text-align: center;">2014-02-23</p>	<p>PART NO.</p> <p style="text-align: center;">HYCW66-SD18-400B</p>
	<p>APPROVED BY:</p> <p style="text-align: center;">邱敏</p>	<p>DATE :</p> <p style="text-align: center;">2014-02-23</p>	<p>DRAW NO:</p> <p style="text-align: center;">HYC-2112291105</p>
			<p>SHEET NO.</p> <p style="text-align: center;">1 OF 1</p>

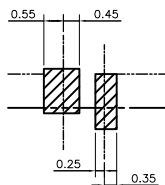


PAD AREA
 KEEP OUT AREA
 No through hole gold, no via hole, no PAD area
 GND PATTEN ONLY
 GULE AREA

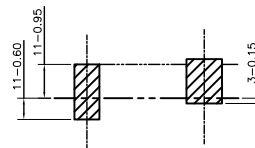
RECOMMENDED PCB LAYOUT (TOP VIEW)
TOLERANCE UNLESS OTHERWISE SPEC ± 0.05



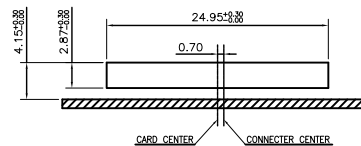
DETAIL J
SCALE 2:1



DETAIL G
SCALE 4:1



DETAIL H
SCALE 4:1

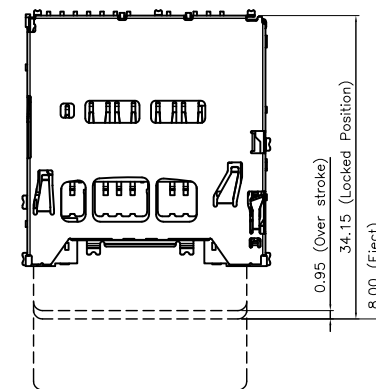
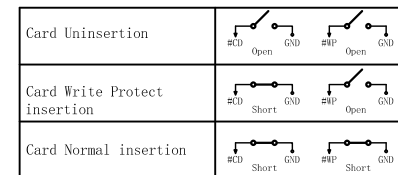


RECOMMENDED ID DIMENSION

Pin Assignment

Pin#	SD Mode	UHS II Mode	SD Express Card	Pin#	SD Mode	UHS II Mode	SD Express Card
#1	CD/DAT3		PERST#	#11		DO+	PCIe_Tx+
#2	CMD			#12		DO-	PCIe_Tx-
#3	VSS1	VSS1	VSS1	#13		VSS4	VSS4
#4	VDD	VDD1	VDD1	#14		VDD2	VDD2
#5	CLK			#15		DI-	PCIe_Rx-
#6	VSS2	VSS2	VSS2	#16		DI+	PCIe_Rx+
#7	DAT0	RCLK+	REFCLK+	#17		VSS5	VSS5
#8	DAT1	RCLK-	REFCLK-	#18			VDD3
#9	DAT2		CLKREQ#	CD			Card Detect
#10		VSS3	VSS3	WP			Write Protect

Function #10, #13, #17 were integrated into 2 pin inMechanical design, and compares to the Layout would be (#10, #13)



Card Push State

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TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X' $\pm 2'$ X.X" $\pm 0.5'$	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SD 7.0 PUSH 4.0H SMT
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW66-SD18-400B
UNIT: mm [inch] SCALE: 1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	